

REVISION HISTORY				
ECO	REV	DESCRIPTION	APPR	DATE
-	2	PRODUCTION FAB	JIM N.	11-2-10

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS
LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER.
MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELCIUS.
7. INSTALL TURRETS AND 4 STAND-OFFS AT FOUR CORNERS AS SHOWN BELOW:

